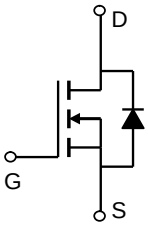
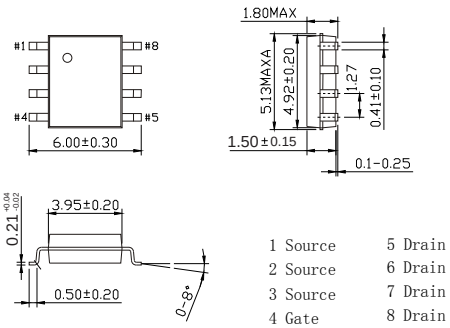
■ Features

- $V_{DS\ (V)}$ = 30V
- I_D = 18 A (V_{GS} = 10V)
- $R_{DS(ON)}$ < 4.5mΩ (V_{GS} = 10V)
- $R_{DS(ON)}$ < 6.5mΩ (V_{GS} = 4.5V)



SOP-8

Unit: mm



1 Source	5 Drain
2 Source	6 Drain
3 Source	7 Drain
4 Gate	8 Drain

■ Absolute Maximum Ratings Ta = 25℃

Parameter		Symbol	Rating	Unit
Drain-Source Voltage		V_{DS}	30	V
Gate-Source Voltage		V_{GS}	±20	
Continuous Drain Current	T_A=25℃	I_D	18	A
	T_A=70℃		15	
Pulsed Drain Current		I_{DM}	80	
Avalanche Current		I_{AR}	30	
Repetitive Avalanche Energy	L=0.3mH	E_{AR}	135	mJ
Power Dissipation	T_A=25℃	P_D	3	W
	T_A=70℃		2.1	
Thermal Resistance.Junction- to-Ambient	t ≤ 10s	R_{thJA}	40	℃/W
	Steady-State		75	
Thermal Resistance.Junction- to-Lead		R_{thJL}	24	
Junction Temperature		T_J	150	℃
Storage Temperature Range		T_{stg}	-55 to 150	

■ Electrical Characteristics Ta = 25℃

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	V_{DSS}	I_D=250μA, V_{GS}=0V	30			V
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS}=30V, V_{GS}=0V			1	μA
		V_{DS}=30V, V_{GS}=0V, T_J=55℃			5	
Gate-Body Leakage Current	I_{GSS}	V_{DS}=0V, V_{GS}=±20V			±100	nA
Gate Threshold Voltage	$V_{GS(th)}$	V_{DS}=V_{GS} , I_D=250μA	1		2.5	V
Static Drain-Source On-Resistance	$R_{DS(ON)}$	V_{GS}=10V, I_D=18A			4.5	mΩ
		V_{GS}=20V, I_D=18A T_J=125℃			7	
		V_{GS}=4.5V, I_D=15A			6.5	
On State Drain Current	$I_{D(ON)}$	V_{GS}=4.5V, V_{DS}=5V	80			A
Forward Transconductance	g_{FS}	V_{DS}=5V, I_D=18A		82		S
Input Capacitance	C_{iss}	V_{GS}=0V, V_{DS}=15V, f=1MHz	4660		7270	pF
Output Capacitance	C_{oss}		425		960	
Reverse Transfer Capacitance	C_{rss}		240		530	
Gate Resistance	R_g	V_{GS}=0V, V_{DS}=0V, f=1MHz	0.2		0.9	Ω
Total Gate Charge (10V)	Q_g	V_{GS}=10V, V_{DS}=15V, I_D=18A	80		124	nC
Total Gate Charge (4.5V)			37		58	
Gate Source Charge	Q_{gs}			18		
Gate Drain Charge	Q_{gd}			15		
Turn-On DelayTime	$t_{d(on)}$	V_{GS}=10V, V_{DS}=15V, R_L=0.83Ω, R_{GEN}=3Ω		12	16	ns
Turn-On Rise Time	t_r			8	12	
Turn-Off DelayTime	$t_{d(off)}$			51.5	70	
Turn-Off Fall Time	t_f			8.8	14	
Body Diode Reverse Recovery Time	t_{rr}	I_F= 18A, dI/dt= 100A/μs		33.5	44	
Body Diode Reverse Recovery Charge	Q_{rr}			22	30	nC
Maximum Body-Diode Continuous Current	I_S				4.5	A
Diode Forward Voltage	V_{SD}	I_S=1A,V_{GS}=0V			1	V

Note : The static characteristics in Figures 1 to 6 are obtained using <300 us pulses, duty cycle 0.5% max.

■ Typical Characterisitics

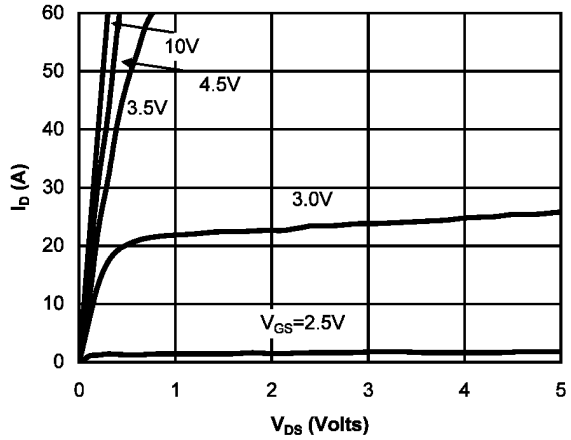


Fig 1: On-Region Characteristics

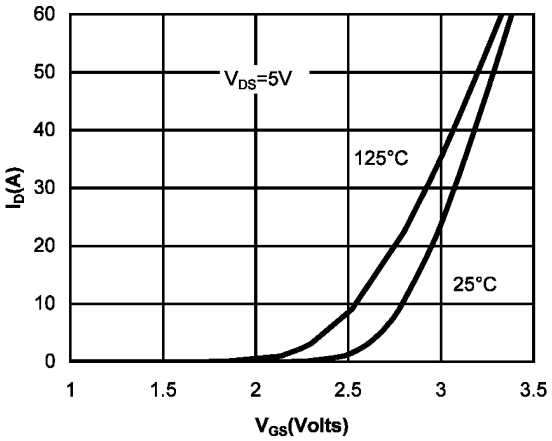


Figure 2: Transfer Characteristics

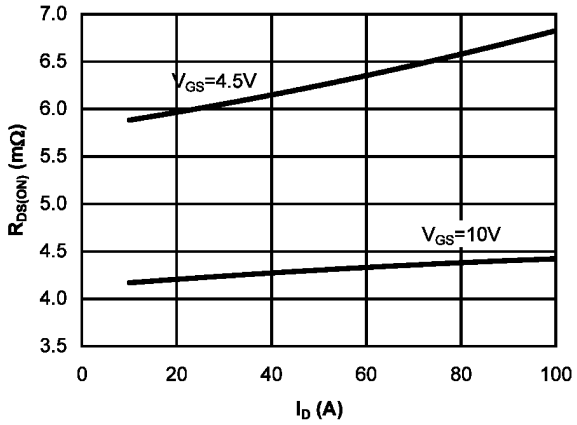


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

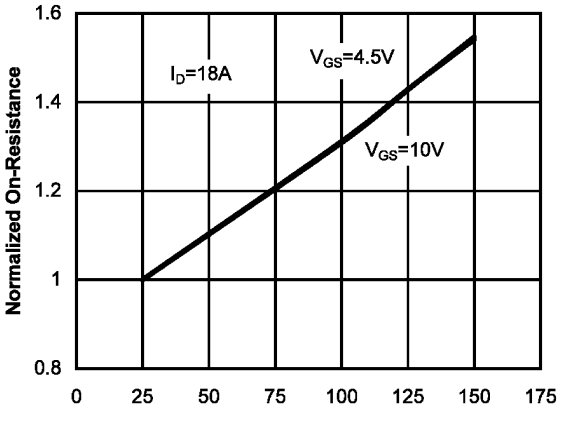


Figure 4: On-Resistance vs. Junction Temperature

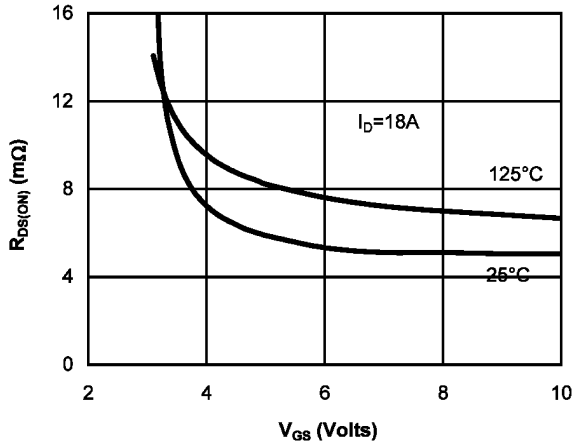


Figure 5: On-Resistance vs. Gate-Source Voltage

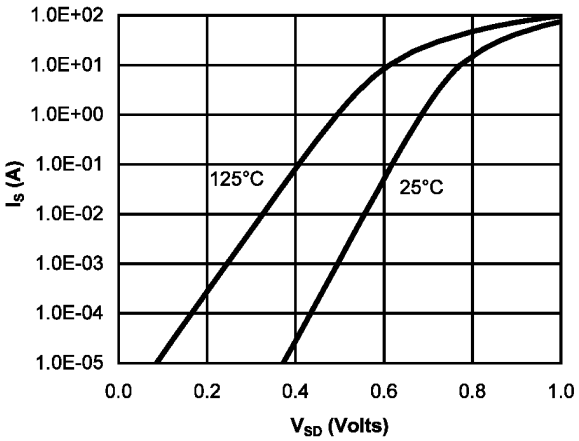


Figure 6: Body-Diode Characteristics

■ Typical Characterisitics

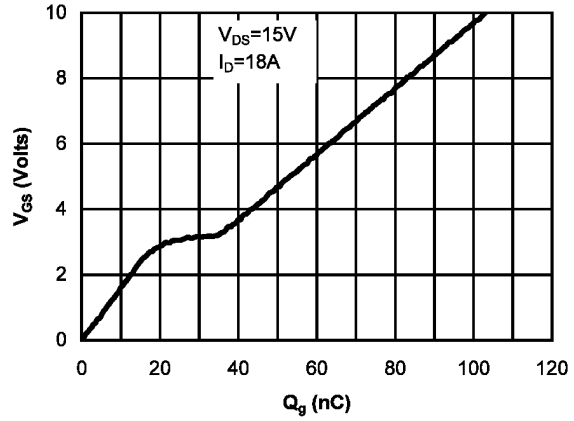


Figure 7: Gate-Charge Characteristics

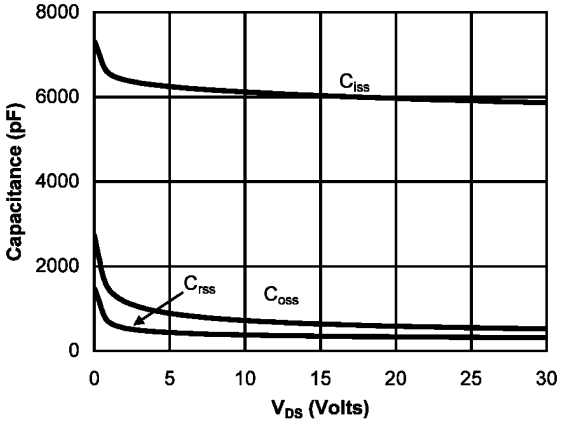


Figure 8: Capacitance Characteristics

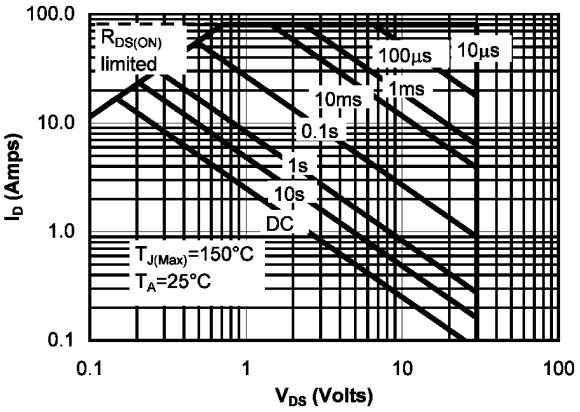


Figure 9: Maximum Forward Biased Safe Operating Area (Note E)

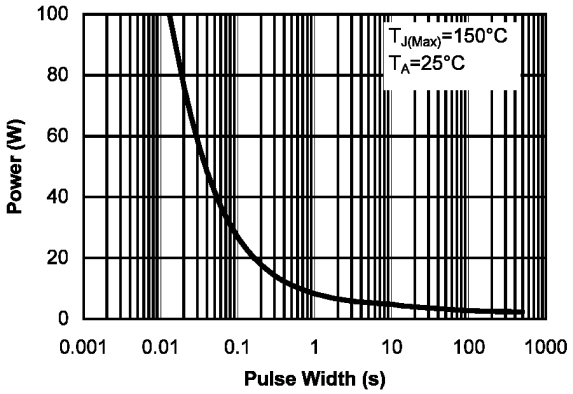


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note E)

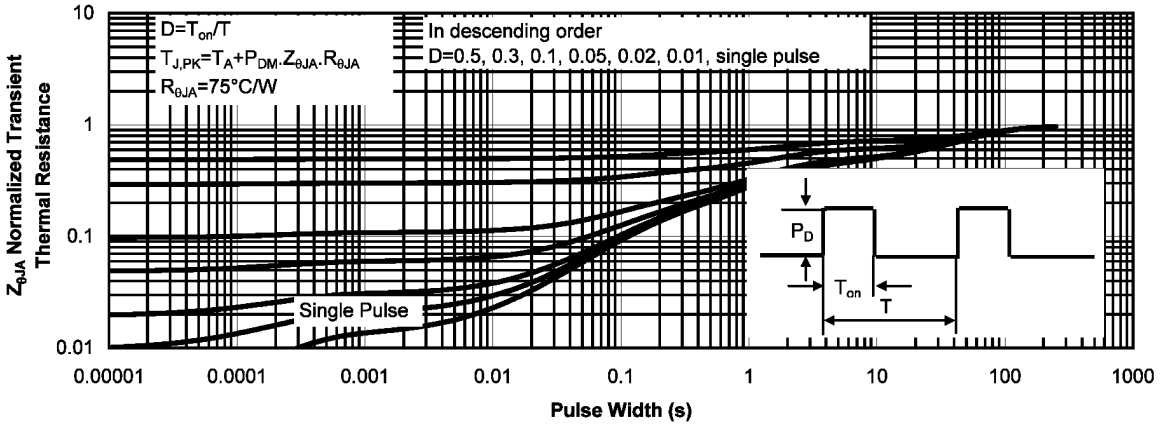


Figure 11: Normalized Maximum Transient Thermal Impedance